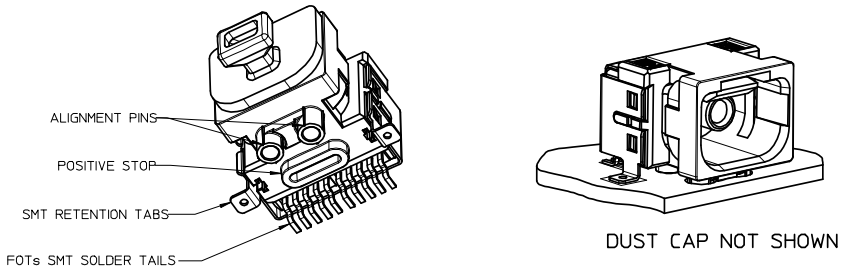
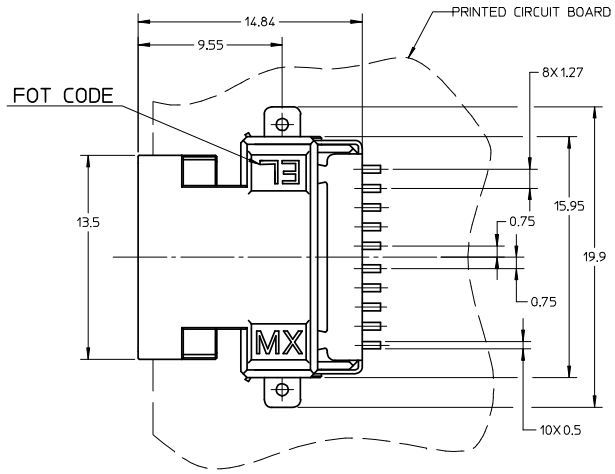
SMI/SMT TRANSCEIVER ASSEMBLY P/N	FOT's TYPE	FOT CODE
1061082200	IEEE-1394/ DIGITAL FDL300K	IE
1061083200	10/100 ETHERNET EDL300K	EL
1061084200	INDUSTRIAL DATA LINK IDL300K	ID

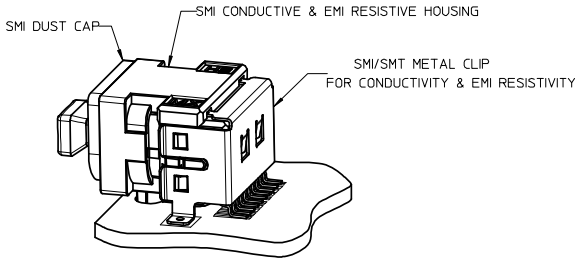


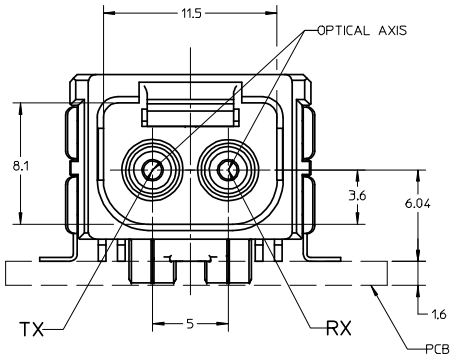
ISOMETRIC VIEWS
SCALE 2.5:1

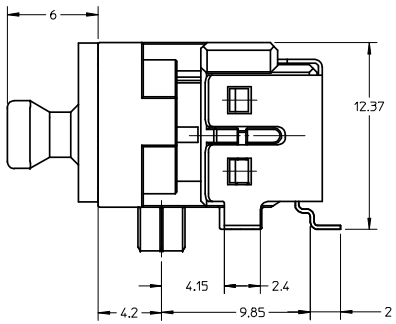
DUST CAP NOT SHOWN

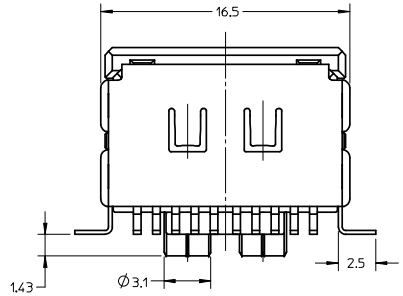


DUST CAP NOT SHOWN

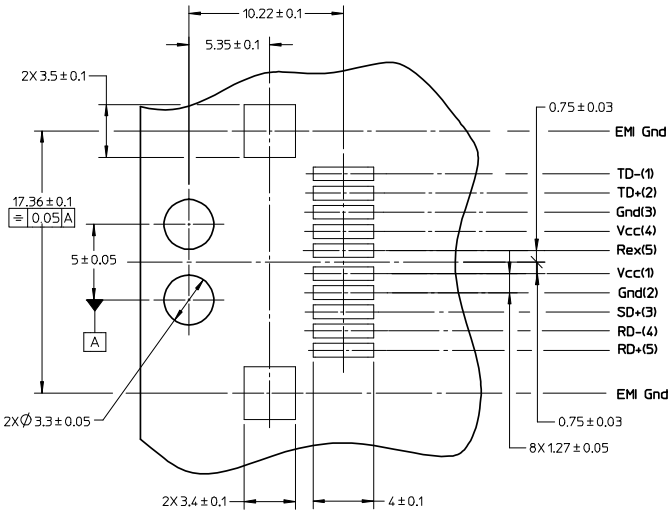








SMI TRANSCEIVER ASSEMBLY
MOUNTED ON THE PCB
DUST CAP NOT SHOWN



RECOMMENDED PCB LAYOUT

NOTE:
1. ALL DIMENSIONS ARE FOR REFERENCE ONLY EXCEPT FOR RECOMMENDED PCB LAYOUT.
2. ATTACHMENT OF THE COMPONENT TO THE PCB SHALL BE VIA HOT BAR, LASER OR IR SOLDERING.
   RE-FLOW OVEN SOLDERING IS NOT APPROVED AT THIS TIME.

ENTER DESCRIPTION
EC NO: MF2008-0555 2008/06/11
DRWN:SMIGO 2008/06/11
CH'KD: 2008/06/26
APPR:SMIGO
DESCRIPTION
B
REV

QUALITY SYMBOLS
▼=0
▽(C)=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± ---	± ---
1 PLACE	± ---	± ---

ANGULAR ±1/2°

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE	MM ONLY
SCALE	4:1
DESIGN UNITS	METRIC
	THIRD ANGLE PROJECTION
DRAWN BY	BG
DATE	09/12/06
CHECKED BY	SE
DATE	9/15/06
APPROVED BY	
DATE	
MATERIAL NO.	SEE TABLE
TITLE	SMI TRANSCEIVER ASSEMBLY SURFACE MOUNT SOLDERING
	MOLEX INCORPORATED
DOCUMENT NO.	SD-106108-X200
SHEET NO.	1 OF 1
SIZE	C

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